

Willkommen bei O-Leading

O-Leading ist bestrebt, Ihr One-Stop-Lösungspartner in der EMS-Lieferkette zu sein, einschließlich Leiterplattendesign, Leiterplattenherstellung und Leiterplattenbestückung (PCB Assembly, PCBA) Wir können vom schnellen Drehungsprototyp zur mittleren u. Massenproduktion stützen. [Leiterplatten-Prototyp-Hersteller China](#)

Im Allgemeinen sind unsere globalen Kunden sehr beeindruckt von unseren Dienstleistungen: schnelle Reaktion, wettbewerbsfähiger Preis und Qualitätsverpflichtung. Die Bereitstellung von mehr wertvollem technischen Service und Gesamtlösung ist der Weg, den O nach vorne weist.

Mit Blick auf die Zukunft wird sich O-Lead wie immer auf die Innovation und Entwicklung der Technologie für die Elektronikfertigung konzentrieren und beharrliche Anstrengungen unternehmen, um erstklassige Dienstleistungen aus einer Hand für PCB und PCBA zu erbringen und mehr Wert für unsere Kunden zu schaffen.

KUPFERPLATTENLÖCHER MINDESTENS .025 AVG, .020MIN .. LÖCHER MÜSSEN GESTOPFT WERDEN

Packung mit farbloser transparenter Luftpolsterfolie, 25 Teile / Beutel, Trockenmittel in die Flanke geben, Feuchtigkeitsanzeigekarte auf die Oberseite legen

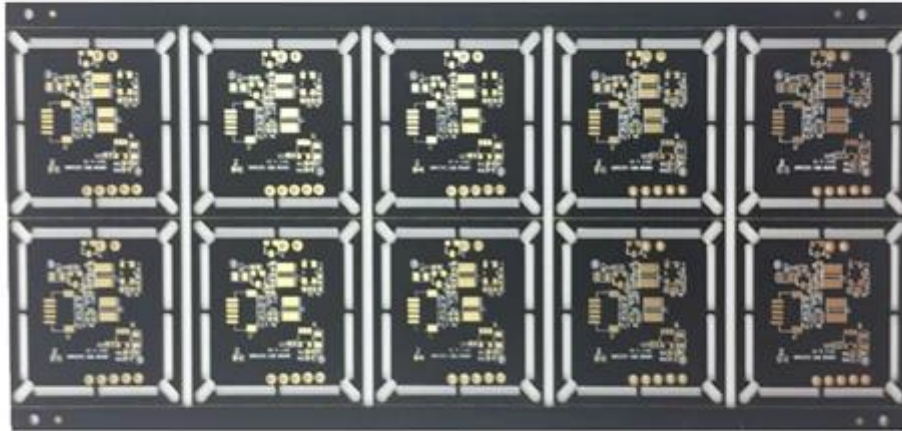
Wir sind ein professioneller Leiterplattenhersteller mit zehn Jahren Erfahrung. Produktpalette: Single-, Double-Side-, Multi-Layer-PCB, Flexible PCB und MCPCB.

Wecan bietet schnellen Prototypenservice - S / S in 24 Stunden, 4-8 Schichten in 48-96 Arbeitsstunden Produktionszeit.

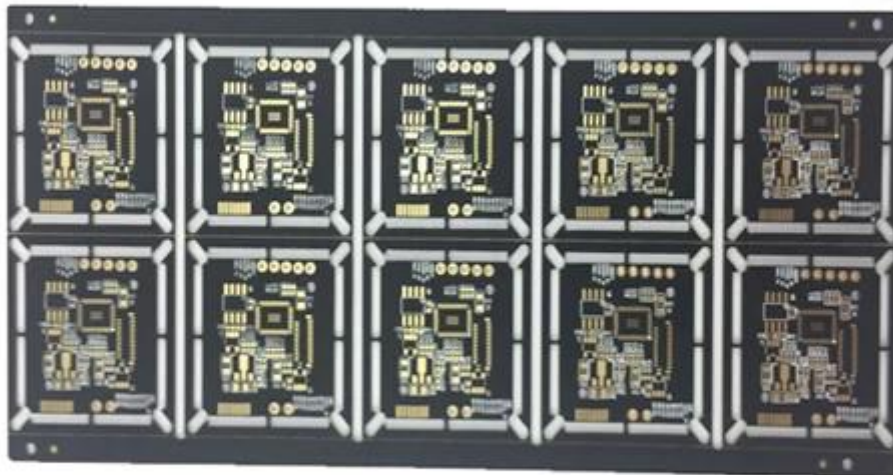
oemmobile ruft PWB-Leiterplatte mit Spg.Versorgungsteil an,[China Starre-flexible Leiterplattenhersteller](#)

Herkunftsort	Guangdong China (Festland)	Markenname	O-führend
Basismaterial	FR-4, Aluminium	Kupferdicke	0,5 Unzen-5 Unzen
Mindest. Lochgröße	0,2 mm	Mindest. Linienbreite	0,2 mm
Oberflächenveredelung	Immersiongold, OSP, bleifreies HASL	Brettstärke	0,1-5 mm
anwendbar auf	LED, Handy, Klimaanlage, Waschmaschinen	Charakter	Industriesteuerungsplatine
Zertifikate	ISO9001, UL, RoHS, SGS	Q / CTN	10PCS-100PCS
Gewicht	0,01 kg - 5 kg	MOQ	10 Stück
Modellnummer	Power Bank Leiterplattenbestückung pcba Hersteller	Mindest. Zeilenabstand	0,2 mm
Farbe	blau, rot, grün, schwarz.gelb	Preis	\$ 0.1- \$ 10
Design-Typ	Kundenanforderung	Größe	0,01 m3 bis 10 m3

[Hersteller von kleinvolumigen Leiterplatten](#)



www.o-leading.com



www.o-leading.com

Unser Team



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT



Zertifizierungen

CICC INSPECTION CERTIFICATION



嘉泰认证

QUALITY MANAGEMENT SYSTEM CERTIFICATE

Certificate No: 18118Q10347R05

We hereby certify that
O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED
 Credit No: 61691591-000-07-18-7
 Registration Add: FLAT/RM 1205 12/F TAI SANG BANK BUILDING 130-132 DES VODEUS ROAD CENTRAL HK
 Business Add: 1213, Floor 13, Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System** Which fulfills the requirements of the following standards
 GB/T19001-2016 idt ISO9001:2015

Scope of certification
 Sales of printed circuit boards

Initial issuance period: February 27, 2018
 Renewal date: April 22, 2019
 This certificate is valid during: April 22, 2019 – February 26, 2021
 This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Second supervision and audit	Qualified mark
-----------------------------	------------------------------	----------------

The certification registration number does not include those production stages which fail to be covered by the relevant effective administrative procedures and qualification procedures stipulated by the client. The effectiveness of this certificate shall be restricted to actual certification scope of CICC. The certificate shall be valid when used together with the qualified mark issued.

The initial issuance of this certification was suspended on the period of CICC. See www.cicc.com.cn for the date of resumption.






CICC INSPECTION CERTIFICATION



嘉泰认证

质量管理体系认证证书

证书号: 18118Q10347R05

兹证明
诚领供应链(香港)有限公司
 统一社会信用代码: 61691591-000-07-18-7
 注册地址: 香港中環德輔道中130-132號大生銀行大廈1205室
 经营地址: 广东惠州惠阳淡水南亨西路财富大厦13楼1313

建立的质量管理体系符合
 GB/T19001-2016 idt ISO9001:2015 质量标准适用条款的要求

认证范围
 印刷线路板的销售

初次获证日期: 2018年02月27日
 换证日期: 2019年04月22日
 证书有效期: 自2019年04月22日至2021年02月26日
 在下列期限内, 未经CICC黏贴合格标贴, 本证书无效

第一次监督	第二次监督	黏贴处
-------	-------	-----

本证书认证范围不包括未取得有效的国家规定的行政许可、资质许可的产品/服务范围; 本证书通过CICC定期监督审核保持, 与年度《保持认证通知书》共同方为有效; 本证书信息可在国家认监委网站: www.cnca.gov.cn 及CICC网站 www.cicc.com.cn 查询。








Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 1 of 6

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ
Date of Sample Received : 22 Mar 2019
Testing Period : 22 Mar 2019 - 30 Mar 2019
Test Requested : Selected test(s) as requested by client.
Test Method : Please refer to next page(s).
Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP) , Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) , and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina
Tina Fan
Approved Signatory



Unless otherwise agreed in writing, this document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.sgs.com/terms-and-conditions.aspx and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at http://www.sgs.com/terms-and-conditions/Electronic-Document.aspx. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that unless he/she expressly agrees to the Company's liability at the time of its intended use, the limits of the Company's liability are restricted to the extent of the Company's liability under the applicable law. This document does not constitute an offer of any financial product or service of the Company. Any disclaimer, limitation, survey or indemnification to the contrary appearing in this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this report refer only to the samples tested.

Member of the SGS Group (SGS SA)



Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 2 of 6

Test Results :

Test Part Description :

Table with 3 columns: Specimen No., SGS Sample ID, Description. Row 1: SN1, SZX19-005304.001, Green"PCB"

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Table with 5 columns: Test Item(s), Limit, Unit, MDL, 0/1. Lists various heavy metals and brominated compounds with their respective limits and detection methods.



Unless otherwise agreed in writing, this document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.sgs.com/terms-and-conditions.aspx and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at http://www.sgs.com/terms-and-conditions/Electronic-Document.aspx. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that unless he/she expressly agrees to the Company's liability at the time of its intended use, the limits of the Company's liability are restricted to the extent of the Company's liability under the applicable law. This document does not constitute an offer of any financial product or service of the Company. Any disclaimer, limitation, survey or indemnification to the contrary appearing in this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this report refer only to the samples tested.

Member of the SGS Group (SGS SA)



ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F
TAI SANG BANK BLDG
130-132 DES VOEUS ROAD
CENTRAL, HONG KONG

Type	Cond Width			SS/ DS/ DSO	Max	Max		Meets UL796	C T	
	Min	Cond	Area		Solder	Flame				
	Min	Edge			Thk		Oper			
mm(in)	mm(in)	mic(mil)	Diam	Limits	Temp	Class	DSR	I		
Multilayer (mass laminate) printed wiring boards.										
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All
Multilayer printed wiring boards.										
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All
Single layer printed wiring boards.										
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

并不是所有出现在本数据库中的公司名称和产品都满足了UL跟踪检验服务的要求。只有带有UL标志的产品，才应该被视为经过UL认证，并满足UL跟踪检验服务的要求。注意查看产品上的标志。

UL允许在线认证目录中所含材料的复制遵循以下条件：1.指南信息、装配、构造、设计、系统和/或认证（文件）必须在不篡改任何数据（或图纸）的情况下完整且无误导性地呈现。2.经UL允许从在线认证目录转载“声明必须出现在所提取材料的邻近位置。此外，转载材料必须包含以下格式的版权声明：“© 2019 UL LLC”

Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

Prozessfähigkeit

PCB-Produktionsmöglichkeiten

Schicht Anzahl: 1Layer-32Layer

Fertige Kupferdicke: 1 / 3oz-12oz

Min. Linienbreite / interner Abstand: 3,0 mil / 3,0 mil

Min. Linienbreite / Abstand extern: 4.0mil / 4.0mil

Maximales Seitenverhältnis: 10: 1

Brettstärke: 0.2mm-5.0mm

Max Panel Größe (Zoll): 635 * 1500 mm

Mindestbohrlochgröße: 4mil

Plated Hole Tolerance: +/- 3mil

Blind / Buried Vias (All-Typen): JA

Via Fill (leitend, nicht leitend): JA

Basismaterial: FR-4, FR-4high Tg. Halogenfreies Material, Rogers, Aluminiumbasis,Polyimid,
Schweres Kupfer

Oberflächen: HASL, OSP, ENIG, HAL-LF, Versilberung,Immersiondose, Goldfinger, Kohletinte

SMT-Produktionsmöglichkeiten

Leiterplattenmaterial: FR-4, CEM-1, CEM-3, Leiterplatte auf Aluminiumbasis
Maximale Leiterplattengröße: 510 x 460 mm
Min PCB Größe: 50x50mm
PWB-Stärke: 0.5mm-4.5mm
Brettstärke: 0.5-4mm
Min. Komponentengröße: 0201
Komponente mit Standardchipgröße: 0603 und größer
Maximale Höhe der Komponente: 15 mm
Min. Steigung: 0,3 mm
Min. BGA-Kugelpitch: 0,4 mm
Platzierungsgenauigkeit: +/- 0,03 mm